## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1341	15/77.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/13 15:25
L2	84	15/77.ccls. and wafer and conve\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/03/13 15:26

First Hit

Previous Doc

Next Doc

Go to Doc#

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L9: Entry 8 of 8

File: DWPI

May 9, 2000

DERWENT-ACC-NO: 2000-399041

DERWENT-WEEK: 200034

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TITLE: Double sided scrubber system used for cleaning a wafer

INVENTOR: HILLMAN, G

PATENT-ASSIGNEE:

ASSIGNEE CODE CREATIVE DESIGN CORP CREAN

PRIORITY-DATA: 1997US-065714P (November 14, 1997), 1998US-0191691 (November 13,

1998)

Search Selected Search ALL Clear

1998US-0191691

PATENT-FAMILY:

PUB-NO PUB-DATE LANGUAGE PAGES MAIN-IPC 013 B08B007/00 П US 6059888 A May 9, 2000

APPLICATION-DATA:

PUB-NO APPL-DATE APPL-NO DESCRIPTOR US 6059888A November 14, 1997 1997US-065714P Provisional

US 6059888A November 13, 1998

INT-CL (IPC): A47 L 1/02; B08 B 7/00

ABSTRACTED-PUB-NO: US 6059888A

BASIC-ABSTRACT:

NOVELTY - The differential frictional forces on the opposite sides of the center of a wafer (202) produces a torque on the wafer about a center causing the wafer to rotate about a central axis (201) transverse to the scrubber axes and the top and bottom surfaces of the wafer. The wafer is kept in position by the constraints (264) as the wafer rotates. The constraints prohibit the translation of the wafer.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for a wafer cleaning method.

USE - Used for cleaning a wafer.

ADVANTAGE - Provides a simple and reliable system for subjecting all surfaces of a wafer to scrubbing.

Central axis 201

Wafer 202

Constraints 264

CHOSEN-DRAWING: Dwg.1/11

TITLE-TERMS: DOUBLE SIDE SCRUB SYSTEM CLEAN WAFER

DERWENT-CLASS: P28 P43 U11 X25

EPI-CODES: U11-C06A1B; X25-H09;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2000-298917

Previous Doc Next Doc Go to Doc#